

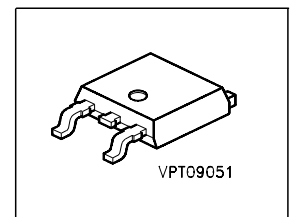
Fast Switching EmCon Diode

Product Summary

V_{RRM}	600	V
I_F	15	A
V_F	1.5	V
T_{jmax}	175	°C

Feature

- 600 V EmCon technology
- Fast recovery
- Soft switching
- Low reverse recovery charge
- Low forward voltage
- 175°C operating temperature
- Easy paralleling
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC⁰⁾ for target applications



Type	Package	Ordering Code	Marking	Pin 1	PIN 2,4	PIN 3
IDD15E60	PG-TO252-3	-	D15E60	NC	C	A

Maximum Ratings, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	600	V
Continuous forward current $T_C = 25\text{ °C}$ $T_C = 90\text{ °C}$	I_F	29.2 19.6	A
Surge non repetitive forward current $T_C = 25\text{ °C}$, $t_p = 10\text{ ms}$, sine halfwave	I_{FSM}	60	A
Maximum repetitive forward current $T_C = 25\text{ °C}$, t_p limited by $t_{j,max}$, $D = 0.5$	I_{FRM}	45	A
Power dissipation $T_C = 25\text{ °C}$ $T_C = 90\text{ °C}$	P_{tot}	83.3 47.2	W
Operating junction temperature	T_j	-40...+175	°C
Storage temperature	T_{stg}	-55...+150	
Soldering temperature 1.6mm (0.063 in.) from case for 10 s	T_S	260	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	1.8	K/W
SMD version, device on PCB:	R_{thJA}				
@ min. footprint		-	-	75	
@ 6 cm ² cooling area ¹⁾		-	-	50	

Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Reverse leakage current	I_R				μA
$V_R=600\text{V}, T_j=25\text{°C}$		-	-	50	
$V_R=600\text{V}, T_j=150\text{°C}$		-	-	1250	
Forward voltage drop	V_F				V
$I_F=15\text{A}, T_j=25\text{°C}$		-	1.5	2	
$I_F=15\text{A}, T_j=150\text{°C}$		-	1.5	-	

⁰J-STD20 and JESD22

¹Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

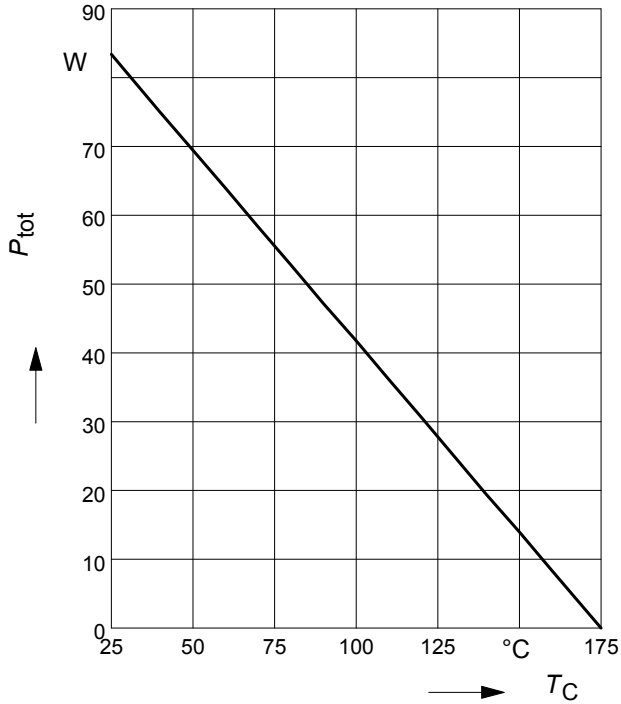
Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Reverse recovery time $V_R=400\text{V}$, $I_F=15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=25^\circ\text{C}$ $V_R=400\text{V}$, $I_F=15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=125^\circ\text{C}$ $V_R=400\text{V}$, $I_F=15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=150^\circ\text{C}$	t_{rr}	-	87 124 131	-	ns
Peak reverse current $V_R=400\text{V}$, $I_F = 15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=25^\circ\text{C}$ $V_R=400\text{V}$, $I_F = 15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=125^\circ\text{C}$ $V_R=400\text{V}$, $I_F = 15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=150^\circ\text{C}$	I_{rrm}	-	13.7 16.4 19.3	-	A
Reverse recovery charge $V_R=400\text{V}$, $I_F=15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=25^\circ\text{C}$ $V_R=400\text{V}$, $I_F = 15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=125^\circ\text{C}$ $V_R=400\text{V}$, $I_F = 15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=150^\circ\text{C}$	Q_{rr}	-	595 995 1104	-	nC
Reverse recovery softness factor $V_R=400\text{V}$, $I_F=15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=25^\circ\text{C}$ $V_R=400\text{V}$, $I_F=15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=125^\circ\text{C}$ $V_R=400\text{V}$, $I_F=15\text{A}$, $di_F/dt=1000\text{A}/\mu\text{s}$, $T_j=150^\circ\text{C}$	S	-	3.6 4.3 4.5	-	

1 Power dissipation

$$P_{\text{tot}} = f(T_C)$$

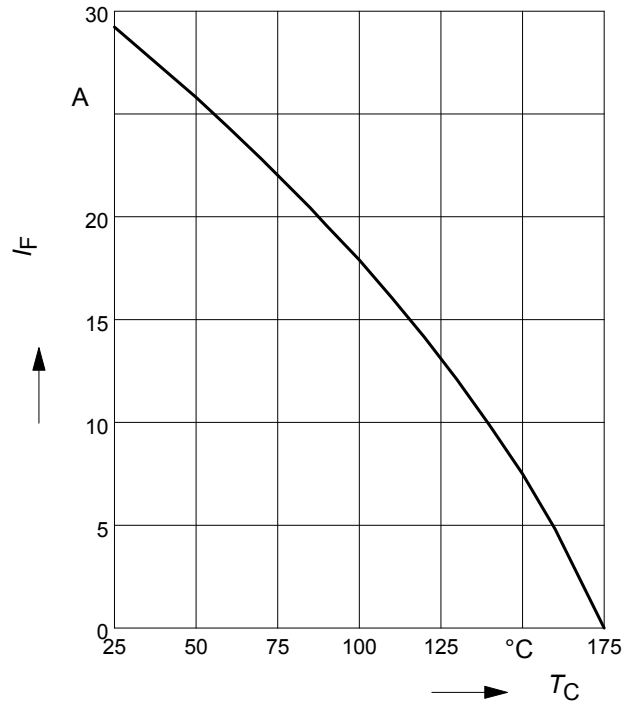
parameter: $T_j \leq 175^\circ\text{C}$



2 Diode forward current

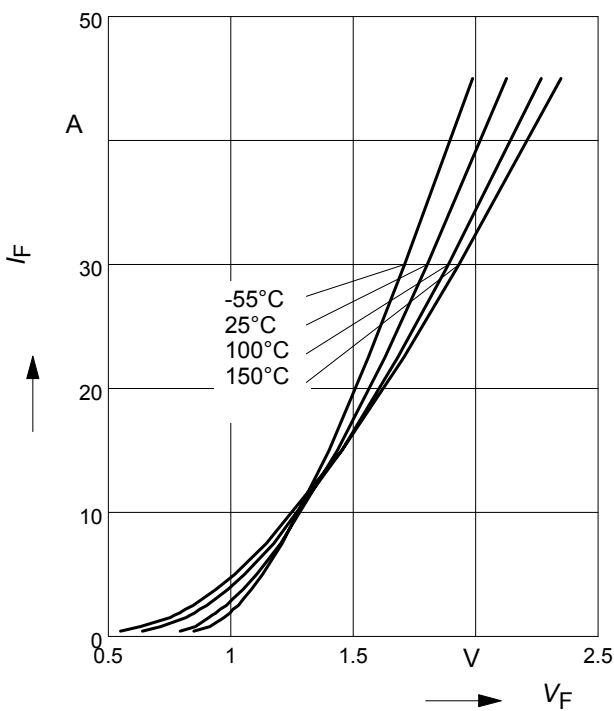
$$I_F = f(T_C)$$

parameter: $T_j \leq 175^\circ\text{C}$



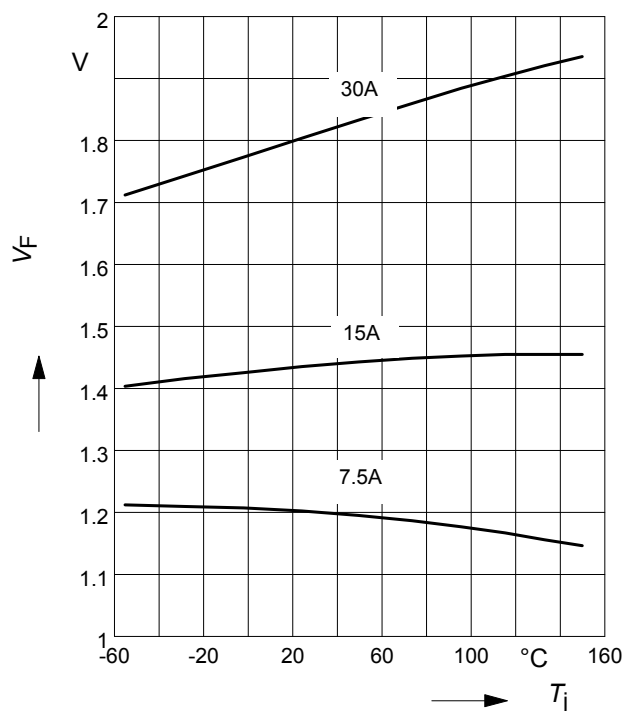
3 Typ. diode forward current

$$I_F = f(V_F)$$



4 Typ. diode forward voltage

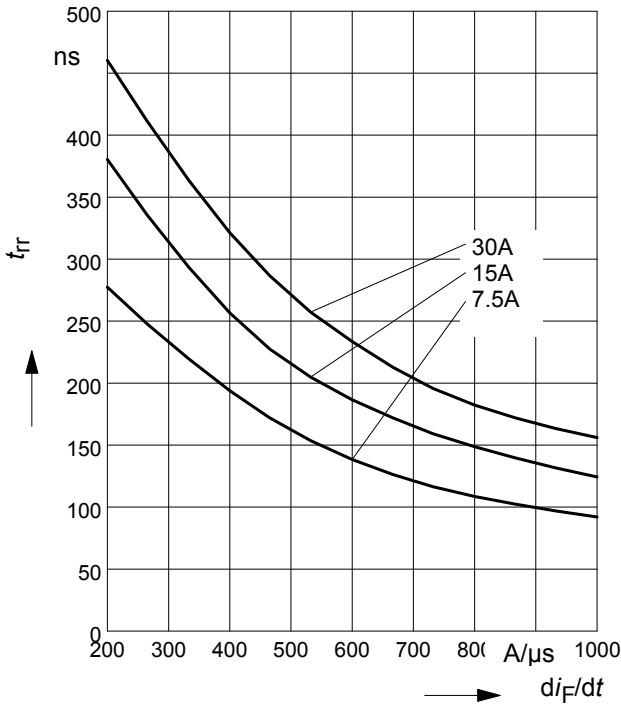
$$V_F = f(T_j)$$



5 Typ. reverse recovery time

$$t_{rr} = f(di_F/dt)$$

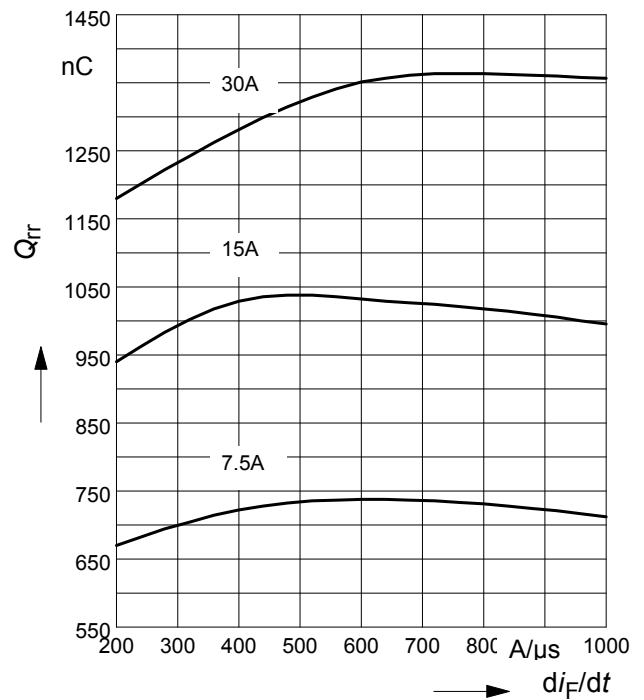
parameter: $V_R = 400V, T_j = 125^\circ C$



6 Typ. reverse recovery charge

$$Q_{rr} = f(di_F/dt)$$

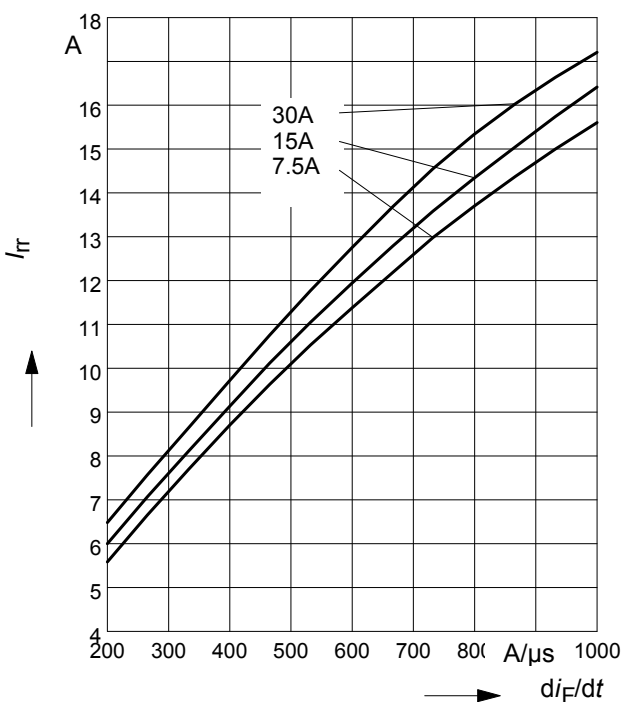
parameter: $V_R = 400V, T_j = 125^\circ C$



7 Typ. reverse recovery current

$$I_{rr} = f(di_F/dt)$$

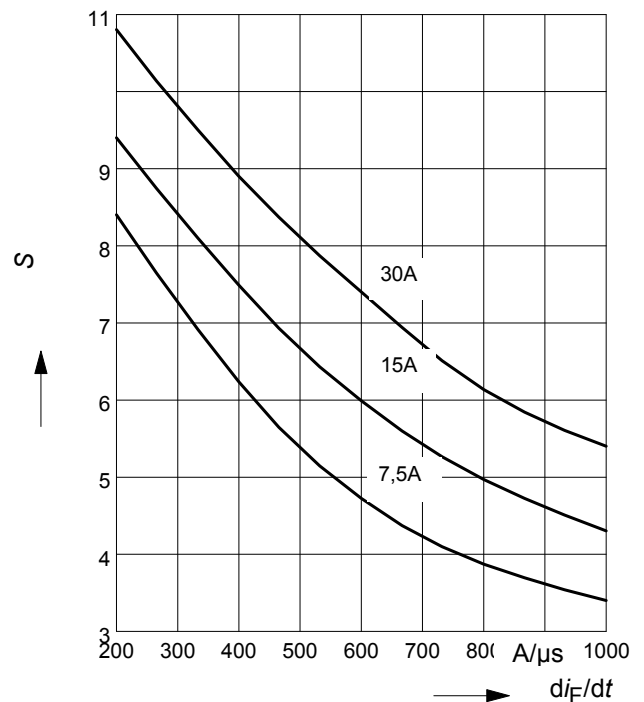
parameter: $V_R = 400V, T_j = 125^\circ C$



8 Typ. reverse recovery softness factor

$$S = f(di_F/dt)$$

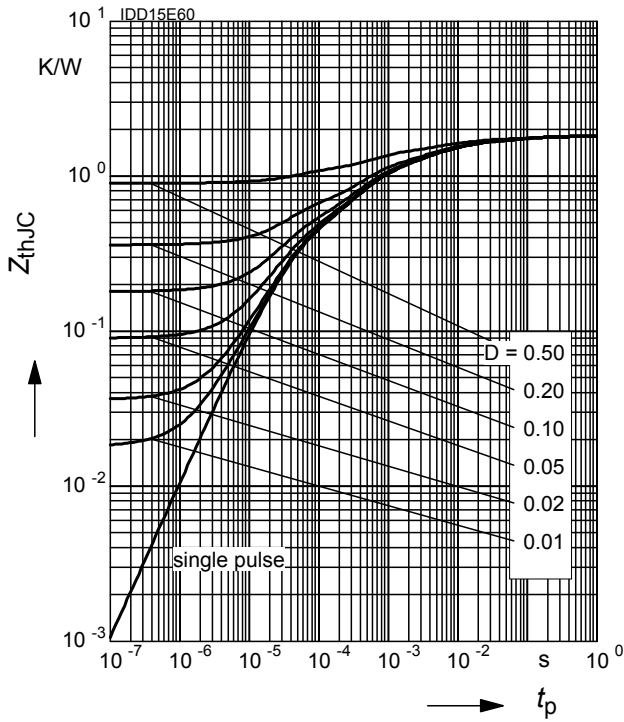
parameter: $V_R = 400V, T_j = 125^\circ C$



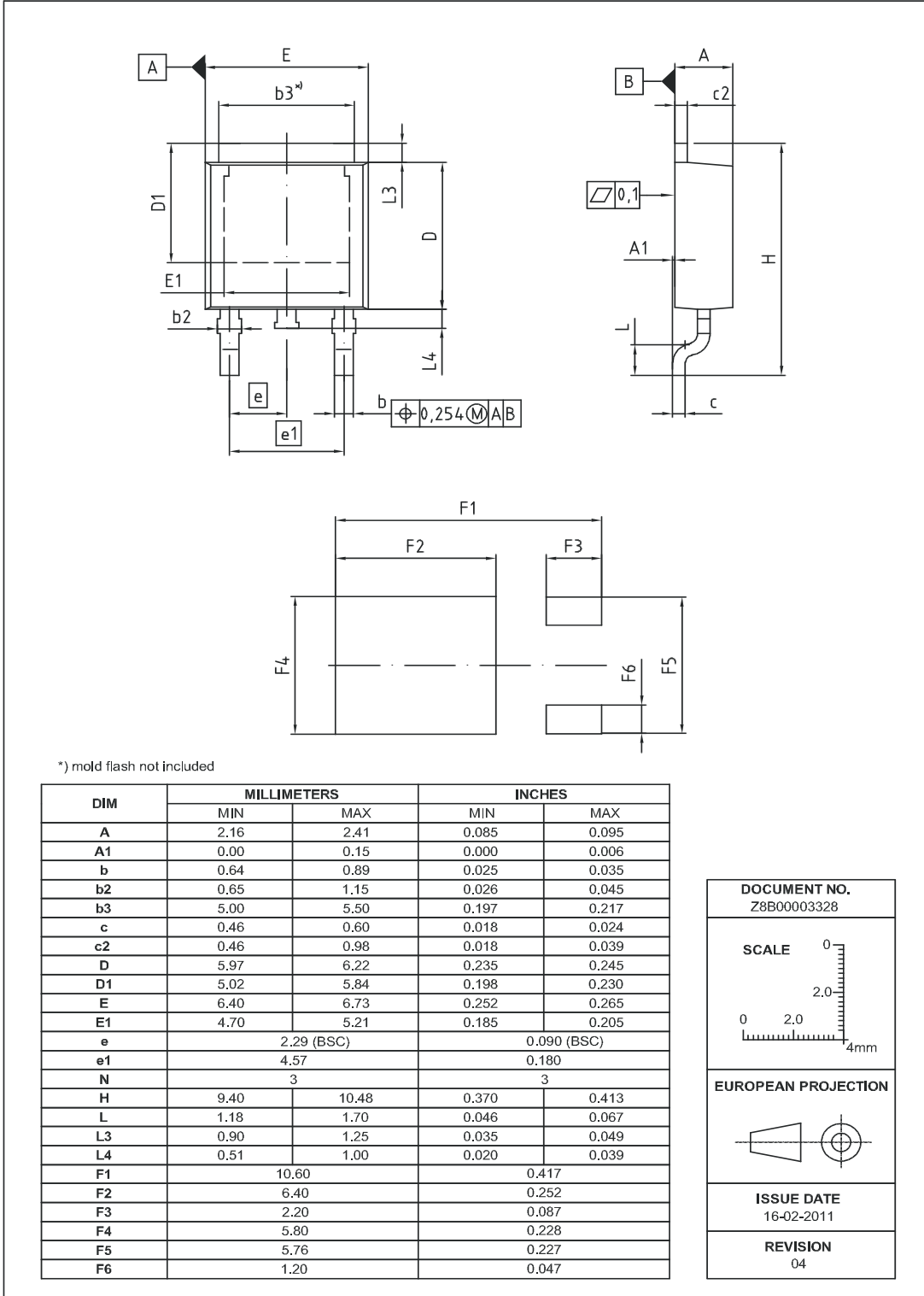
9 Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$

parameter : $D = t_p/T$



PG-TO252 -3



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